

Title (en)

BRASS ALLOY POWDER, BRASS ALLOY EXTRUDED MATERIAL AND METHOD FOR PRODUCING THE BRASS ALLOY EXTRUDED MATERIAL

Title (de)

MESSINGLEGIERUNGSPULVER, EXTRUDIERTES MESSINGLEGIERUNGSMATERIAL UND VERFAHREN ZUR HERSTELLUNG DES EXTRUDIERTEN MESSINGLEGIERUNGSMATERIALS

Title (fr)

POUDRE DE LAITON SPÉCIAL, MATIÈRE EXTRUDÉE DE LAITON SPÉCIAL ET PROCÉDÉ POUR LA FABRICATION DE LA MATIÈRE EXTRUDÉE DE LAITON SPÉCIAL

Publication

EP 2275582 A4 20140820 (EN)

Application

EP 09742676 A 20090424

Priority

- JP 2009058142 W 20090424
- JP 2008121475 A 20080507

Abstract (en)

[origin: EP2275582A1] Brass alloy powder has a brass composition formed by a mixed phase of \pm -phase and 2 -phase, and contains 0.5 to 5.0 mass % of chromium. The chromium includes a component that is solid-solved in a mother phase of brass, and a component that is precipitated at crystal grain boundaries.

IPC 8 full level

B22F 9/08 (2006.01); **B21C 23/00** (2006.01); **B21C 23/01** (2006.01); **B22F 1/00** (2006.01); **B22F 3/20** (2006.01); **C22C 1/04** (2006.01); **C22C 9/04** (2006.01); **C22F 1/00** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP US)

B21C 23/002 (2013.01 - EP US); **C22C 1/0425** (2013.01 - EP US); **C22C 9/04** (2013.01 - EP US); **C22F 1/08** (2013.01 - EP US); **B22F 2998/10** (2013.01 - EP US)

C-Set (source: EP US)

B22F 2998/10 + **B22F 2009/0828** + **B22F 3/20**

Citation (search report)

- [I] JP H07118777 A 19950509 - TAIHO KOGYO CO LTD, et al
- [I] US 4285739 A 19810825 - DERUYTTERE ANDRE E A, et al
- [I] WO 2007013428 A1 20070201 - SAN ETSU METALS CO LTD [JP], et al & US 2009092517 A1 20090409 - KOSAKA YOSHIHARU [JP], et al
- [IA] JP S6213549 A 19870122 - HITACHI LTD
- [A] JP H0853725 A 19960227 - TAIHO KOGYO CO LTD
- See also references of WO 2009136552A1

Cited by

IT202000004480A1; ITBS20130119A1; ITUA20163561A1; RU2733620C2; WO2017199147A1; US11351607B2; US11679436B2

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EP 09742676 A 20090424; CN 200980116310 A 20090424; JP 2009058142 W 20090424; JP 2010511043 A 20090424; US 99125909 A 20090424